

LISTING OF THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-8. (Canceled).

9. (Previously Presented) A micromechanical component, comprising:

a body having a hollow space and a region of porous silicon located contiguously thereto, wherein the region of porous silicon is provided for lowering a pressure prevailing in the hollow space, in that gases are bound to the porous silicon.

10. (Previously Presented) The component as recited in Claim 9, wherein the porous silicon binds oxygen by forming silicon dioxide already in response to a low temperature.

11. (Previously Presented) The component as recited in Claim 9, further comprising:

a first substrate;

a second substrate; and

an intermediate layer provided between the first substrate and the second.

12. (Previously Presented) The component as recited in Claim 11, wherein the first substrate and the second substrate are joined to one another in such a way that they are hermetically sealed at the intermediate layer.

13. (Previously Presented) The component as recited in Claim 9, further comprising:

a first substrate; and

a membrane, wherein:

the hollow space is provided between the membrane and the first substrate,

and

the region of porous silicon is provided in the first substrate.

14. (Previously Presented) A method for manufacturing a component, comprising:

producing a micromechanical structure in a first substrate;

producing in a second substrate a region of porous silicon;

joining the first substrate and the second substrate; and

lowering a pressure by activating the region of porous silicon.

15. (Previously Presented) A method for manufacturing a component, comprising:
- producing a region of porous silicon in a first substrate;
 - producing in the first substrate a micromechanical structure; and
 - joining a second substrate to the first substrate; and
 - lowering a pressure by activating the region of porous silicon.
16. (Previously Presented) A method for manufacturing a component, comprising:
- producing a region of porous silicon in a first substrate;
 - producing in the first substrate a micromechanical structure; and
 - lowering a pressure by activating the region of porous silicon.
- 17-19. (Canceled).
20. (Currently Amended) The micromechanical component of Claim [[1]] 2, further comprising:
- a micromechanical structure configured as a pressure sensor.
21. (Previously Presented) The method of Claim 14, wherein the micromechanical structure is configured as a pressure sensor.